



NEXCOM International Co., Ltd.

Intelligent Platform & Services Business Unit

Visual Edge Computer

NDiS B362

User Manual

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PREFACE

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Disclaimer

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Acknowledgements

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Regulatory Compliance Statements

This section provides the FCC compliance statement for Class A devices and describes how to keep the system CE compliant.

Declaration of Conformity

FCC

This equipment has been tested and verified to comply with the limits for a Class A digital device, pursuant to Part 15 of FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. Operation of this equipment in a residential area (domestic environment) is likely to cause harmful interference, in which case the user will be required to correct the interference (take adequate measures) at their own expense.

CE

The product(s) described in this manual complies with all applicable European Union (CE) directives if it has a CE marking. For computer systems to remain CE compliant, only CE-compliant parts may be used. Maintaining CE compliance also requires proper cable and cabling techniques.

RoHS Compliance



NEXCOM RoHS Environmental Policy and Status Update

NEXCOM is a global citizen for building the digital infrastructure. We are committed to providing green products and services, which are compliant with European Union RoHS (Restriction on Use of Hazardous Substance in Electronic Equipment) directive 2011/65/EU, to be your trusted green partner and to protect our environment.

RoHS restricts the use of Lead (Pb) < 0.1% or 1,000ppm, Mercury (Hg) < 0.1% or 1,000ppm, Cadmium (Cd) < 0.01% or 100ppm, Hexavalent Chromium (Cr6+) < 0.1% or 1,000ppm, Polybrominated biphenyls (PBB) < 0.1% or 1,000ppm, and Polybrominated diphenyl Ethers (PBDE) < 0.1% or 1,000ppm.

In order to meet the RoHS compliant directives, NEXCOM has established an engineering and manufacturing task force to implement the introduction of green products. The task force will ensure that we follow the standard NEXCOM development procedure and that all the new RoHS components and new manufacturing processes maintain the highest industry quality levels for which NEXCOM are renowned.

The model selection criteria will be based on market demand. Vendors and suppliers will ensure that all designed components will be RoHS compliant.

How to recognize NEXCOM RoHS Products?

For existing products where there are non-RoHS and RoHS versions, the suffix "(LF)" will be added to the compliant product name.

All new product models launched after January 2013 will be RoHS compliant. They will use the usual NEXCOM naming convention.

Warranty and RMA

NEXCOM Warranty Period

NEXCOM manufactures products that are new or equivalent to new in accordance with industry standard. NEXCOM warrants that products will be free from defect in material and workmanship for 2 years, beginning on the date of invoice by NEXCOM. HCP series products (Blade Server) which are manufactured by NEXCOM are covered by a three year warranty period.

NEXCOM Return Merchandise Authorization (RMA)

- Customers shall enclose the “NEXCOM RMA Service Form” with the returned packages.
- Customers must collect all the information about the problems encountered and note anything abnormal or, print out any on-screen messages, and describe the problems on the “NEXCOM RMA Service Form” for the RMA number apply process.
- Customers can send back the faulty products with or without accessories (manuals, cable, etc.) and any components from the card, such as CPU and RAM. If the components were suspected as part of the problems, please note clearly which components are included. Otherwise, NEXCOM is not responsible for the devices/parts.
- Customers are responsible for the safe packaging of defective products, making sure it is durable enough to be resistant against further damage and deterioration during transportation. In case of damages occurred during transportation, the repair is treated as “Out of Warranty.”
- Any products returned by NEXCOM to other locations besides the customers’ site will bear an extra charge and will be billed to the customer.

Repair Service Charges for Out-of-Warranty Products

NEXCOM will charge for out-of-warranty products in two categories, one is basic diagnostic fee and another is component (product) fee.

Repair Service Charges for Out-of-Warranty Products

NEXCOM will charge for out-of-warranty products in two categories, one is basic diagnostic fee and another is component (product) fee.

System Level

- Component fee: NEXCOM will only charge for main components such as SMD chip, BGA chip, etc. Passive components will be repaired for free, ex: resistor, capacitor.
- Items will be replaced with NEXCOM products if the original one cannot be repaired. Ex: motherboard, power supply, etc.
- Replace with 3rd party products if needed.
- If RMA goods can not be repaired, NEXCOM will return it to the customer without any charge.

Board Level

- Component fee: NEXCOM will only charge for main components, such as SMD chip, BGA chip, etc. Passive components will be repaired for free, ex: resistors, capacitors.
- If RMA goods can not be repaired, NEXCOM will return it to the customer without any charge.

Warnings

Read and adhere to all warnings, cautions, and notices in this guide and the documentation supplied with the chassis, power supply, and accessory modules. If the instructions for the chassis and power supply are inconsistent with these instructions or the instructions for accessory modules, contact the supplier to find out how you can ensure that your computer meets safety and regulatory requirements.

Cautions

Electrostatic discharge (ESD) can damage system components. Do the described procedures only at an ESD workstation. If no such station is available, you can provide some ESD protection by wearing an antistatic wrist strap and attaching it to a metal part of the computer chassis.

Safety Information

Before installing and using the device, note the following precautions:

- Read all instructions carefully.
- Do not place the unit on an unstable surface, cart, or stand.
- Follow all warnings and cautions in this manual.
- When replacing parts, ensure that your service technician uses parts specified by the manufacturer.
- Avoid using the system near water, in direct sunlight, or near a heating device.
- The load of the system unit does not solely rely for support from the rackmounts located on the sides. Firm support from the bottom is highly necessary in order to provide balance stability.
- The computer is provided with a battery-powered real-time clock circuit. There is a danger of explosion if battery is incorrectly replaced. Replace only with the same or equivalent type recommended by the manufacturer. Discard used batteries according to the manufacturer's instructions.

Installation Recommendations

Ensure you have a stable, clean working environment. Dust and dirt can get into components and cause a malfunction. Use containers to keep small components separated.

Adequate lighting and proper tools can prevent you from accidentally damaging the internal components. Most of the procedures that follow require only a few simple tools, including the following:

- A Philips screwdriver
- A flat-tipped screwdriver
- A grounding strap
- An anti-static pad

Using your fingers can disconnect most of the connections. It is recommended that you do not use needle-nose pliers to disconnect connections as these can damage the soft metal or plastic parts of the connectors.

Safety Precautions

1. Read these safety instructions carefully.
2. Keep this User Manual for later reference.
3. Disconnect this equipment from any AC outlet before cleaning. Use a damp cloth. Do not use liquid or spray detergents for cleaning.
4. For plug-in equipment, the power outlet socket must be located near the equipment and must be easily accessible.
5. Keep this equipment away from humidity.
6. Put this equipment on a stable surface during installation. Dropping it or letting it fall may cause damage.
7. The openings on the enclosure are for air convection to protect the equipment from overheating. **DO NOT COVER THE OPENINGS.**
8. Make sure the voltage of the power source is correct before connecting the equipment to the power outlet.
9. Place the power cord in a way so that people will not step on it. Do not place anything on top of the power cord. Use a power cord that has been approved for use with the product and that it matches the voltage and current marked on the product's electrical range label. The voltage and current rating of the cord must be greater than the voltage and current rating marked on the product.
10. All cautions and warnings on the equipment should be noted.
11. If the equipment is not used for a long time, disconnect it from the power source to avoid damage by transient overvoltage.
12. Never pour any liquid into an opening. This may cause fire or electrical shock.
13. Never open the equipment. For safety reasons, the equipment should be opened only by qualified service personnel.
14. If one of the following situations arises, get the equipment checked by service personnel:
 - a. The power cord or plug is damaged.
 - b. Liquid has penetrated into the equipment.
 - c. The equipment has been exposed to moisture.
 - d. The equipment does not work well, or you cannot get it to work according to the user's manual.
 - e. The equipment has been dropped and damaged.
 - f. The equipment has obvious signs of breakage.
15. Do not place heavy objects on the equipment.
16. The unit uses a three-wire ground cable which is equipped with a third pin to ground the unit and prevent electric shock. Do not defeat the purpose of this pin. If your outlet does not support this kind of plug, contact your electrician to replace your obsolete outlet.
17. **CAUTION: DANGER OF EXPLOSION IF BATTERY IS INCORRECTLY REPLACED. REPLACE ONLY WITH THE SAME OR EQUIVALENT TYPE RECOMMENDED BY THE MANUFACTURER. DISCARD USED BATTERIES ACCORDING TO THE MANUFACTURER'S INSTRUCTIONS.**

Technical Support and Assistance

1. For the most updated information of NEXCOM products, visit NEXCOM's website at www.nexcom.com.
2. For technical issues that require contacting our technical support team or sales representative, please have the following information ready before calling:
 - Product name and serial number
 - Detailed information of the peripheral devices
 - Detailed information of the installed software (operating system, version, application software, etc.)
 - A complete description of the problem
 - The exact wordings of the error messages

Warning!

1. Handling the unit: carry the unit with both hands and handle it with care.
2. Maintenance: to keep the unit clean, use only approved cleaning products or clean with a dry cloth.

Conventions Used in this Manual



Warning:

Information about certain situations, which if not observed, can cause personal injury. This will prevent injury to yourself when performing a task.



Caution:

Information to avoid damaging components or losing data.



Note:

Provides additional information to complete a task easily.

Global Service Contact Information

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Package Contents

Before continuing, verify that the NDiS B362 package that you received is complete. Your package should have all the items listed in the following table.

Item	Part Number	Name	Qty
1	10W00B36204X0 or	NDiS B362-125U	1
	10W00B36202X0 or	NDiS B362-165U	
	10W00B36200X0 or	NDiS B362-155U	
	10W00B36203X0	NDiS B362-135U	
2	7400096009X00	POWER ADAPTER FSP: FSP096-AHAN3 (9NA0961442)	1
3	50311F0144X00	I HEAD SCREW LONG FEI: M3x4mm NI NYLOK	1
4	5040430536X00	M.2 EXTEND NUT BRACKET for 5G/LTE module	1
5	5060200570X00	Thermal pad: 30x20x3mm for WiFi module	1
6	5060200596X00	Thermal pad: 40x30x3mm for 5G/LTE module	1
7	5060200720X00	Thermal pad: 60x20x3mm for SSD and RAM	2

Ordering Information

The following information below provides ordering information for NDiS B362.

NDiS B362-125U (P/N:10W00B36204X0)

Fanless Visual Edge Computer, Core™ Ultra 5 Processor 125U

NDiS B362-165U (P/N:10W00B36202X0)

Fanless Visual Edge Computer, Core™ Ultra 7 Processor 165U

NDiS B362-155U (P/N:10W00B36200X0)

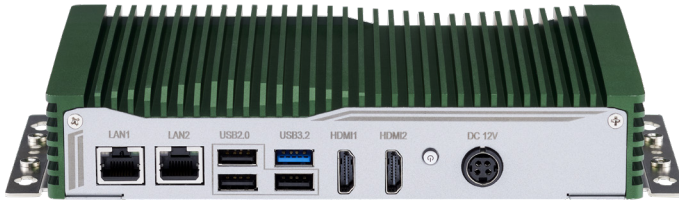
Fanless Visual Edge Computer, Core™ Ultra 7 Processor 155U

NDiS B362-135U (P/N:10W00B36203X0)

Fanless Visual Edge Computer, Core™ Ultra 5 Processor 135U

CHAPTER 1: PRODUCT INTRODUCTION

Overview



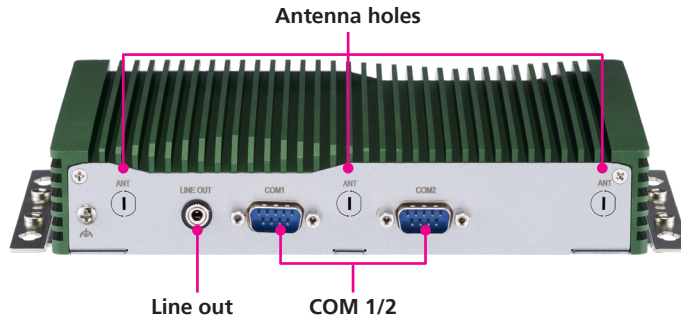
Digital transformation continues to evolve in 2024. Thus NDIS B362 Visual Edge Computer, powered by Intel® Core™ Ultra 7 or 5 processor which embed with a dedicated NPU for AI inference. By optimizing workloads across CPU, GPU, and NPU leading to achieve up to 32 TOPS of AI computing power while minimizing energy consumption. Dual HDMI® 2.0 ports, stunning visuals are guaranteed. Diverse I/O interfaces to enable a broad spectrum of AI applications. Designed to withstand extreme temperatures from 0°C to 60°C, NDIS B362 is perfect for semi-outdoor application such as self-service kiosks, Smart beverage station, smart recycling machine and intelligent parking system.

Key Features

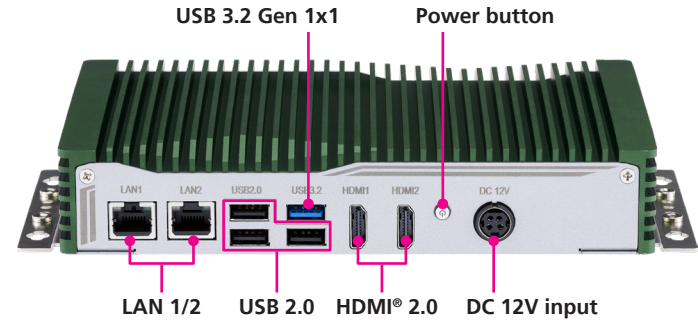
- Intel® Core™ Ultra U Processor Series
- Support Intel® AMT technology (Intel Ultra7 165U and Intel Ultra 5 135U only)
- 2 x DDR5 SO-DIMM, up to 96GB
- 2 x HDMI® 2.0 output, up to 4096x2160@60Hz
- Dual Intel® LAN ports
- 1 x USB 3.2 Gen 1x1 and 3 x USB 2.0
- TPM 2.0 on board for security
- 1 x M.2 Key B 3052/2242 for optional 5G/LTE module
- 1 x M.2 Key E 2230 for optional Wi-Fi module
- 1 x M.2 Key M 2280 for optional SSD
- Support +12V DC power input

Physical Features

Front Panel



Rear Panel



Hardware Specifications

CPU Support

- Intel® Core Ultra 7, Meteor Lake 165U, 12-core/4.9GHz
- Intel® Core Ultra 7, Meteor Lake 155U, 12-core/4.8GHz
- Intel® Core Ultra 5, Meteor Lake 135U, 12-core/4.4GHz
- Intel® Core Ultra 5, Meteor Lake 125U, 12-core/4.3GHz

* Only 165U and 135U support Intel® AMT

Main Memory

- 2 x DDR5 SO-DIMM, up to 96GB

Graphics & Display

- Intel® Graphics
- 2 x HDMI® 2.0, up to 4096x2160@60Hz

Storage

- 1 x M.2 2280 Key M (PCIe x4 NVME/SATA), supports optional storage module

Expansion

- 1 x M.2 Key E 2230 for optional Wi-Fi module
- 1 x M.2 Key B 3052/2242 for optional 5G/LTE module (PCIe 3.0 x1, USB 3.0, USB 2.0)

I/O Interface-Rear

- 1 x Power button with LED
- 2 x HDMI® 2.0, up to 4096x2160@60Hz

- 1 x 2.5GbE RJ45 Port, Intel® i226
- 1 x GbE RJ45 Port, Intel® I219
- 1 x USB 3.2 Gen 1x1, Type-A
- 3 x USB 2.0
- +12V DC In

I/O Interface-Front

- 1 x Line out
- 2 x COM Port, supports RS-232/RS-422/RS-485
- 3 x Antenna hole

I/O Interface-Internal

- 2 x 6-pin header for 4 x USB 2.0 port
- 4 x 9-pin header for COM port RS-232 (Reserved)
- 1 x 10-pin header for GPIO, 4 x DI, 4 x DO
- 1 x 4-pin header for 2W/4Ω speaker out
- 1 x 9-pin header for Mic in and Line out
- 1 x 2-pin header for Reset

Mechanical & Dimension

- System Unit
 - Dimension: 200mm (W) x 140mm (D) x 37mm (H) w/o bracket
 - Net weight: 1.26 kgs/Unit
- Package Carton
 - Dimension: 300mm (W) x 270mm (D) x 205mm (H)
 - Gross weight : 2.54 kg (1 unit/per carton)

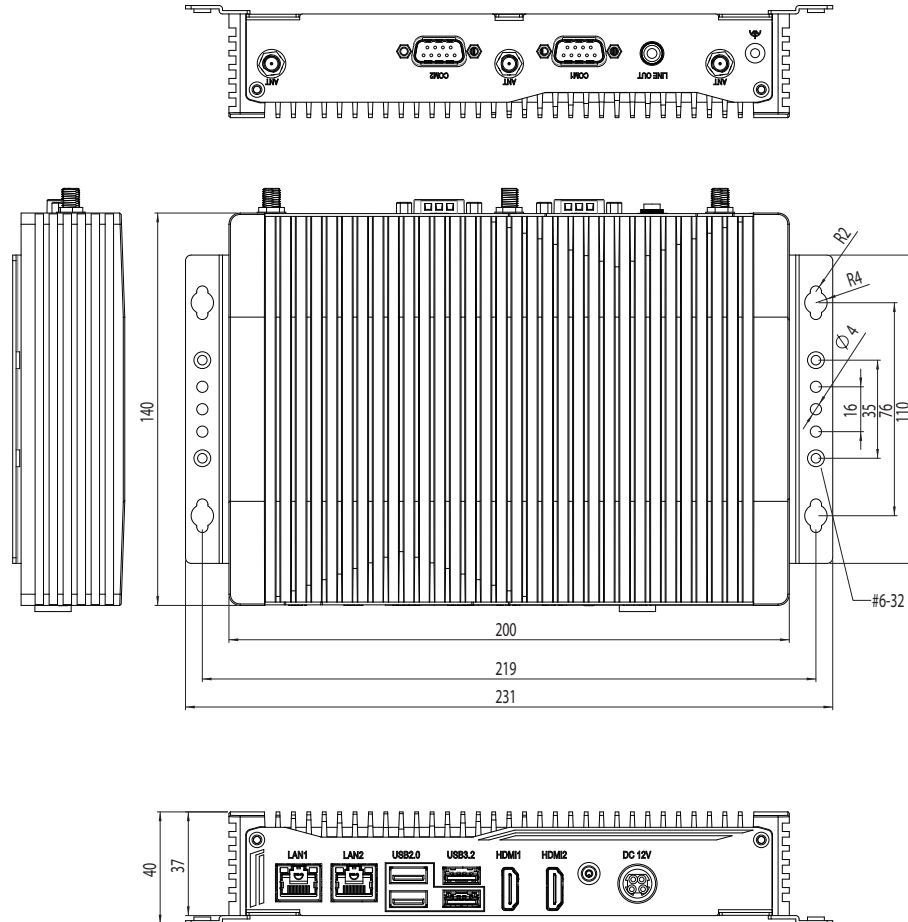
Power Supply

- Nominal Voltage: +12V DC
- +12V, 96W AC/DC power adapter in carton

Environment

- Operating temperature:
 - Ambient with air flow: 0°C~55°C (Core Ultra 7-165U & 155U)
 - Ambient with air flow: 0°C~60°C (Core Ultra 5-135U & 125U)
 - Storage temperature: -20°C~80°C
- Relative humidity: 0%~90% (non-condensing)
- Shock protection: 50G peak acceleration, 11ms according to IEC 60068-2-27
- Vibration protection
 - Random: 2Grms@5~500Hz, IEC 60068-2-64
 - Sinusoidal: 2G@5~500Hz, IEC 60068-2-6

Mechanical Dimensions



CHAPTER 2: JUMPERS AND CONNECTORS

This chapter describes how to set the jumpers and connectors on the NDiS B362 motherboard.

Before You Begin

- Ensure you have a stable, clean working environment. Dust and dirt can get into components and cause a malfunction. Use containers to keep small components separated.
- Adequate lighting and proper tools can prevent you from accidentally damaging the internal components. Most of the procedures that follow require only a few simple tools, including the following:
 - A Philips screwdriver
 - A flat-tipped screwdriver
 - A set of jewelers screwdrivers
 - A grounding strap
 - An anti-static pad
- Using your fingers can disconnect most of the connections. It is recommended that you do not use needle-nosed pliers to disconnect connections as these can damage the soft metal or plastic parts of the connectors.
- Before working on internal components, make sure that the power is off. Ground yourself before touching any internal components, by touching a metal object. Static electricity can damage many of the electronic components. Humid environments tend to have less static electricity than

dry environments. A grounding strap is warranted whenever danger of static electricity exists.

Precautions

Computer components and electronic circuit boards can be damaged by discharges of static electricity. Working on computers that are still connected to a power supply can be extremely dangerous.

Follow the guidelines below to avoid damage to your computer or yourself:

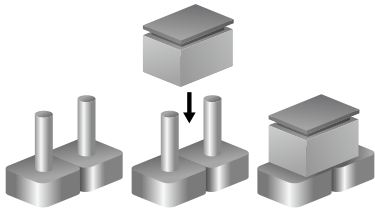
- Always disconnect the unit from the power outlet whenever you are working inside the case.
- If possible, wear a grounded wrist strap when you are working inside the computer case. Alternatively, discharge any static electricity by touching the bare metal chassis of the unit case, or the bare metal body of any other grounded appliance.
- Hold electronic circuit boards by the edges only. Do not touch the components on the board unless it is necessary to do so. Don't flex or stress the circuit board.
- Leave all components inside the static-proof packaging that they shipped with until they are ready for installation.
- Use correct screws and do not over tighten screws.

Jumper Settings

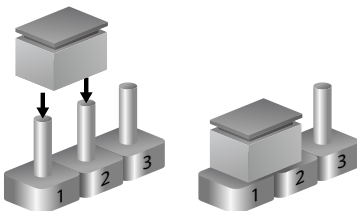
A jumper is the simplest kind of electric switch. It consists of two metal pins and a cap. When setting the jumpers, ensure that the jumper caps are placed on the correct pins. When the jumper cap is placed on both pins, the jumper is short. If you remove the jumper cap, or place the jumper cap on just one pin, the jumper is open.

Refer to the illustrations below for examples of what the 2-pin and 3-pin jumpers look like when they are short (on) and open (off).

Two-Pin Jumpers: Open (Left) and Short (Right)

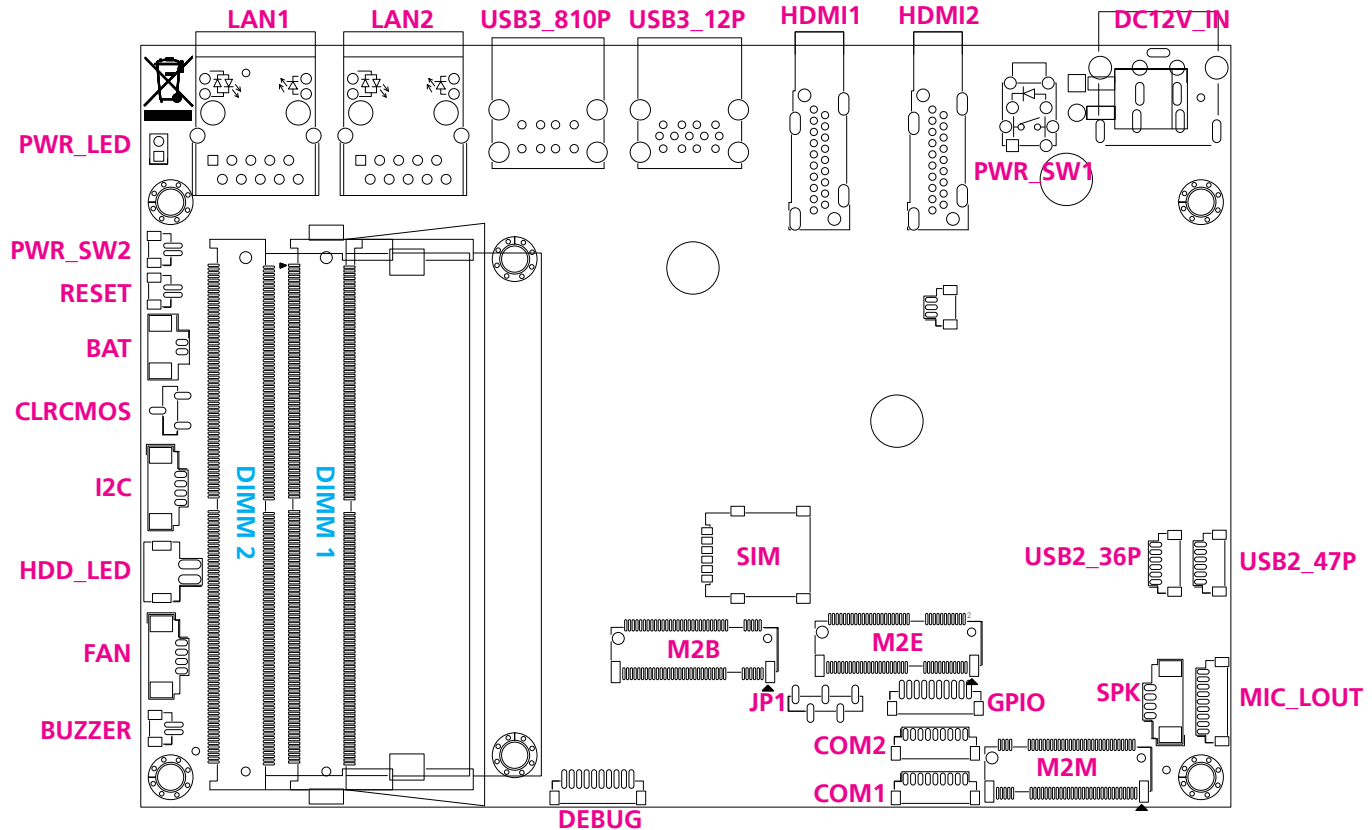


Three-Pin Jumpers: Pins 1 and 2 are Short



Locations of the Jumpers and Connectors for NDiS B362

The figure below shows the location of the NDiS B362 mainboard jumpers and connectors. Refer to the figure below for detailed information on pin settings and definitions marked in pink.



Jumpers Settings

Clear CMOS

Connector location: CLRCMOS



Pin	Settings
1-2 On	Normal (default)
2-3 On	Clear CMOS

COM2 Voltage Select

Connector location: JP1



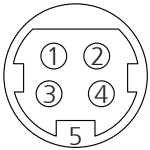
Pin	Settings
1-2 On	COM2 RI Pin is ring (default)
2-3 On	COM2 RI pin is +5V
4-5 On	COM2 RI pin is +12V

Connector Pin Definition

External I/O Interfaces

DC Power Input

Connector location: DC12V_IN

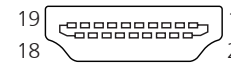


Pin	Definition	Pin	Definition
1	+12V	2	+12V
3	GND	4	GND
5	CHASSIS		

HDMI®

Connector type: HDMI®

Connector location: HDMI1, HDMI2

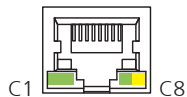


Pin	Definition	Pin	Definition
1	TX2P	2	GND
3	TX2N	4	TX1P
5	GND	6	TX1N
7	TX0P	8	GND
9	TX0N	10	CLK_P
11	GND	12	CLK_N
13	NC	14	NC
15	SCL	16	SDA
17	GND	18	+5V
19	HPD		
MH1	CGND	MH2	CGND
MH3	CGND	MH4	CGND
NH1	N.C.	NH2	N.C.

LAN

Connector type: RJ45 port with LEDs

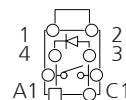
Connector location: LAN1, LAN2



System Power Button 1

Connector type: 1x4 4-pin header

Connector location: PWR_SW1



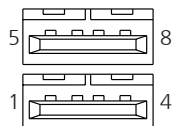
Pin	Definition	Pin	Definition
1	MDI0P	2	MDI0N
3	MDI1P	4	MDI1N
5	TCT	6	TCTG
7	MDI2P	8	MDI2N
9	MDI3P	10	MDI3N
11	LED_ACT_POWER	12	LED_ACT#
13	LED_LINK100M#	14	LED_LINK2.5G#
MH1	CGND	MH2	CGND
NH1	NC	NH2	NC

Pin	Definition	Pin	Definition
1	SWITCH_NODE1	2	SWITCH_NODE2
3	SWITCH_NODE2	4	SWITCH_NODE1
C1	LED-	A1	LED+
MH1	N.C.	MH2	N.C.

USB 2.0

Connector type: Dual USB 2.0 Type-A

Connector location: USB2_810P

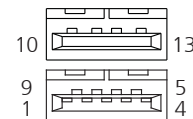


Pin	Definition	Pin	Definition
1	+5V	2	USB2_D1-
3	USB2_D1+	4	GND
5	+5V	6	USB2_D2-
7	USB2_D2+	8	GND
MH1	CGND	MH2	CGND
MH3	CGND	MH4	CGND

USB Combo

Connector type: USB 3.2 + USB 2.0 Type-A

Connector location: USB3_12P



Pin	Definition	Pin	Definition
1	+5V	2	USB2_D0-
3	USB2_D0+	4	GND
5	USB3_RX-	6	USB3_RX+
7	GND	8	USB3_TX-
9	USB3_TX+	10	+5V
11	USB2_D1-	12	USB2_D1+
13	GND		
MH1	CGND	MH2	CGND
MH3	CGND	MH4	CGND

Internal Connectors

Battery Connector

Connector type: 1x2 2-pin header, 1.25mm pitch

Connector location: BAT



Pin	Definition
1	GND
2	+VBAT

Buzzer

Connector type: 1x2 2-pin header, 1.0mm pitch

Connector location: BUZZER

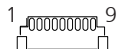


Pin	Definition	Pin	Definition
1	BUZZER-	2	BUZZER+

COM Port

Connector type: 1x9 9-pin header, 1.0mm pitch

Connector location: COM1, COM2

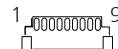


Pin	RS-232	RS-422	RS-485
1	RI#		
2	CTS#		
3	RTS#		
4	DSR#		
5	GND		
6	DTR#	RX-	
7	TXD#	RX+	
8	RXD#	TX+	D+
9	DCD#	TX-	D-

COM Port

Connector type: 1x9 9-pin header, 1.0mm pitch

Connector location: COM3, COM4, COM5, COM6



Pin	RS-232
1	RI#
2	CTS#
3	RTS#
4	DSR#
5	GND
6	DTR#
7	TXD#
8	RXD#
9	DCD#

Fan

Connector type: 1x4 4-pin header, 1.25mm pitch

Connector location: FAN

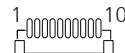


Pin	Definition	Pin	Definition
1	GND	2	+12V
3	FAN SPEED DETECT	4	FAN SPEED CONTROL

GPIO

Connector type: 1x10 10-pin header, 1.0mm pitch

Connector location: GPIO



Pin	Definition	Pin	Definition
1	+5V	2	GND
3	GPO0	4	GPO1
5	GPO2	6	GPO3
7	GPI0	8	GPI1
9	GPI2	10	GPI3

HDD LED

Connector type: 1x2 2-pin header, 2.0mm pitch

Connector location: HDD_LED



Pin	Definition	Pin	Definition
1	LED+	2	LED-

I2C

Connector type: 1x4 4-pin header, 1.25mm pitch

Connector location: I2C

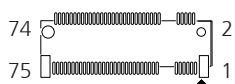


Pin	Definition	Pin	Definition
1	GND	2	I2C_DAT
3	I2C_CLK	4	+5V

M.2 Key B

Connector type: M.2 Key B 3042/3052

Connector location: M2B



Pin	Definition	Pin	Definition
1	CONFIG3	2	3.3V
3	GND	4	3.3V
5	GND	6	POWER_OFF#
7	USB2_P	8	W_DISABLE1#
9	USB2_N	10	LED#
11	GND		
Key			
		20	PCIe/USB Select Pin
21	CONFIG0	22	NC
23	NC	24	NC
25	NC	26	W_DISABLE2#
27	GND	28	NC

Pin	Definition	Pin	Definition
29	USB3_RXN	30	UIM_RESET
31	USB3_RXP	32	UIM_CLK
33	GND	34	UIM_DATA
35	USB3_TXN	36	UIM_PWR
37	USB3_TXP	38	NC
39	GND	40	NC
41	PCIe_RXN	42	NC
43	PCIe_RXP	44	NC
45	GND	46	NC
47	PCIe_TXN	48	NC
49	PCIe_TXP	50	PCIe_RST# (3.3V)
51	GND	52	PCIe_CLKREQ#

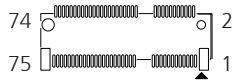
Continued on next page

Pin	Definition	Pin	Definition
53	REFCLKN	54	PCIE_WAKE#
55	REFCLKP	56	NC
57	GND	58	NC
59	NC	60	NC
61	NC	62	NC
63	NC	64	NC
65	NC	66	NC
67	LTE_RST# (1.8V)	68	SUS_CLK
69	CONFIG1	70	3.3V
71	GND	72	3.3V
73	GND	74	3.3V
75	CONFIG2		

M.2 Key E

Connector type: M.2 Key E 2230

Connector location: M2E



Pin	Definition	Pin	Definition
1	GND	2	3.3V_1
3	USB_D+	4	3.3V_2
5	USB_D-	6	LED1#
7	GND2	8	PCM_CLK
9	SDIO_CLK	10	PCM_SYNC
11	SDIO_CMD	12	PCM_IN
13	SDIO_DATA0	14	PCM_OUT
15	SDIO_DATA1	16	LED2#
17	SDIO_DATA2	18	GND3
19	SDIO_DATA3	20	UART_WAKE#
21	SDIO_WAKE#	22	UART_RXD
23	SDIO_RESET#		

Pin	Definition	Pin	Definition
Key			
		32	UART_TXD
33	GND4	34	UART_CTS
35	PETP0	36	UART_RTS
37	PETN0	38	RESERVED_1
39	GND5	40	RESERVED_2
41	PERP0	42	RESERVED_3
43	PERN0	44	COEX3
45	GND6	46	COEX2
47	REFCLKP0	48	COEX1
49	REFCLKN0	50	SUSCLK
51	GND7	52	PERST0#

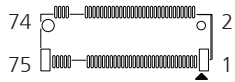
Continued on next page

Pin	Definition	Pin	Definition
53	CLKREQ0#	54	W_DISABLE2#
55	PEWAKE0#	56	W_DISABLE1#
57	GND8	58	I2C_DATA
59	PETP1	60	I2C_CLK
61	PETN1	62	ALERT#
63	GND9	64	RESERVED
65	PERP1	66	UIM_SWP
67	PERN1	68	UIM_POWER_SNK
69	GND10	70	UIM_POWER_SRC
71	PEFCLKP1	72	3.3V_3
73	PEFCLKN1	74	3.3V_4
75	GND11		

M.2 Key M

Connector type: M.2 Key M 2280

Connector location: M2M



Pin	Definition	Pin	Definition
1	GND	2	VCC3
3	GND	4	VCC3
5	PCIE_RX3N	6	NC
7	PCIE_RX3P	8	NC
9	GND	10	LED#
11	PCIE_TX3N	12	VCC3
13	PCIE_TX3P	14	VCC3
15	GND	16	VCC3
17	PCIE_RX2N	18	VCC3
19	PCIE_RX2P	20	NC
21	GND	22	NC
23	PCIE_TX2N	24	NC

Pin	Definition	Pin	Definition
25	PCIE_TX2P	26	NC
27	GND	28	NC
29	PCIE_RX1N	30	NC
31	PCIE_RX1P	32	NC
33	GND	34	NC
35	PCIE_TX1N	36	NC
37	PCIE_TX1P	38	DEVSLP
39	GND	40	NC
41	SATA_RXP (PCIE_RX0P)	42	NC
43	SATA_RXN (PCIE_RX0N)	44	NC
45	GND	46	NC
47	SATA_TXN (PCIE_TX0N)	48	NC

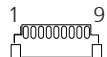
Continued on next page

Pin	Definition	Pin	Definition
49	SATA_TXP (PCIE_TXOP)	50	PERST#
51	GND	52	PECLKREQ#
53	REFCLKN	54	PEWAKE#
55	REFCLKP	56	NC
57	GND	58	NC
Key			
67	NC	68	SUSCLK
69	PEDET	70	VCC3
71	GND	72	VCC3
73	GND	74	VCC3
75	GND		

MIC and Line Out

Connector type: 1x9 9-pin header, 1.0mm pitch

Connector location: MIC_LOUT



Pin	Definition	Pin	Definition
1	LINE_OUT_R	2	LINE_JD
3	AGND	4	LINE_OUT_L
5	AGND	6	MIC_IN_R
7	MIC_JD	8	MIC_IN_L
9	AGND		

Power LED (optional)

Connector type: 1x2 2-pin header, 2.0mm pitch

Connector location: PWR_LED



Pin	Definition	Pin	Definition
1	LED+	2	LED-

Power Button 2

Connector type: 1x2 2-pin header, 1.0mm pitch

Connector location: PWR_SW2



Pin	Definition	Pin	Definition
1	GND	2	PWRBTN#

System Reset

Connector type: 1x2 2-pin header, 1.0mm pitch

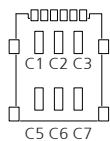
Connector location: RESET



Pin	Definition	Pin	Definition
1	GND	2	RESET#

SIM Card

Connector location: SIM

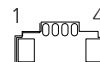


Pin	Definition	Pin	Definition
C1	VCC	C2	RST
C3	CLK		
C5	GND	C6	VPP
C7	I/O		

Speaker (with Amplifier)

Connector type: 1x4 4-pin header, 1.25mm pitch

Connector location: SPK



Pin	Definition	Pin	Definition
1	OUT_L+	2	OUT_L-
3	OUT_R+	4	OUT_R-

USB 2.0

Connector type: 1x6 6-pin header, 1.0mm pitch

Connector location: USB2_36P



Pin	Definition	Pin	Definition
1	GND	2	USB_A-
3	USB_A+	4	USB_B-
5	USB_B+	6	+5V

USB 2.0

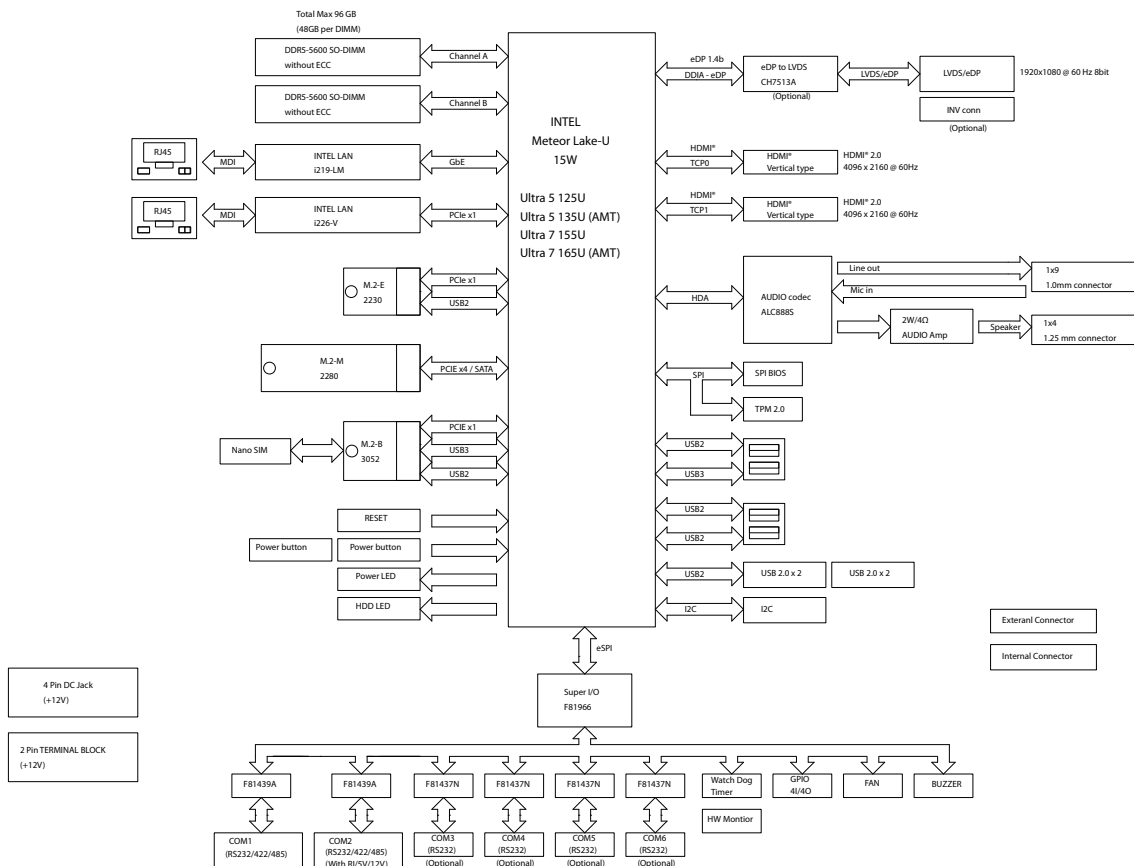
Connector type: Connector type: 1x6 6-pin header, 1.0mm pitch

Connector location: USB2_47P



Pin	Definition	Pin	Definition
1	GND	2	USB_A-
3	USB_A+	4	USB_B-
5	USB_B+	6	+5V

Block Diagram



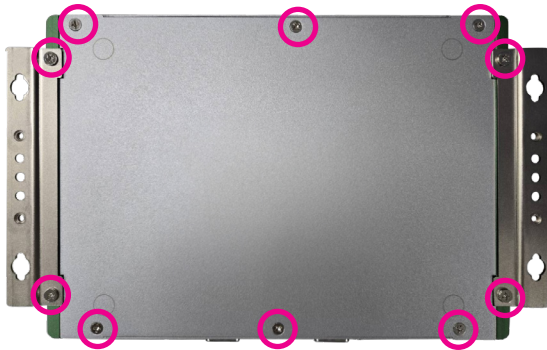
CHAPTER 3: SYSTEM SETUP

Removing the Chassis Cover



Prior to removing the chassis cover, make sure the unit's power is off and disconnected from the power sources to prevent electric shock or system damage.

1. The screws on bottom are used to secure the cover to the chassis. Remove these 10 screws and put them in a safe place for later use.

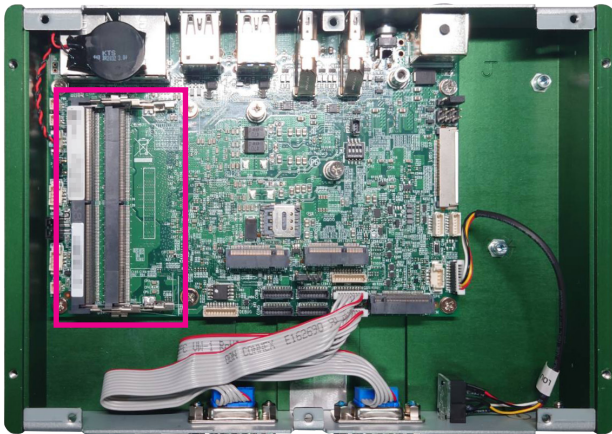


2. With the screws removed, lift up the cover and remove it from the chassis.

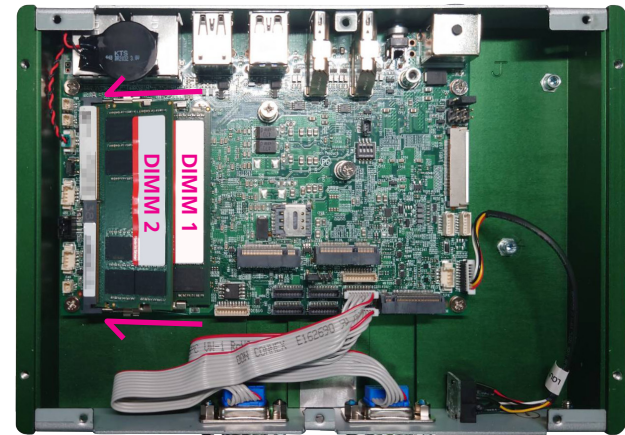


Installing SO-DIMM Memory Modules

1. Locate the SO-DIMM socket on the board.



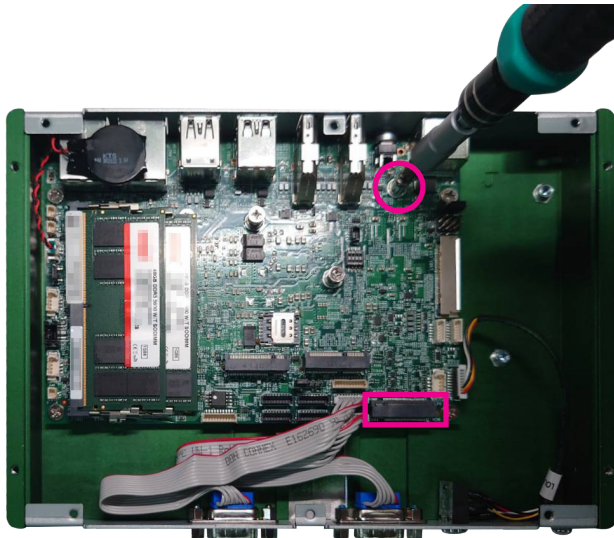
2. Insert the module into the socket at an approximately 30 degrees angle. The ejector tabs at the ends of the socket will automatically snap into the locked position to hold the module in place.



1. If there is only a single memory module required, please install it in [DIMM slot 2](#).
2. It's recommended that you install memory modules of the same brand, speed, and capacity if you want to plug them into both of the slots.
3. The total supported memory is up to 96GB.

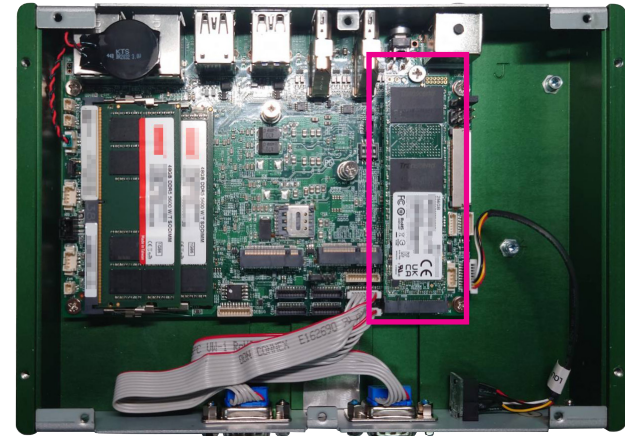
Installing an M.2 Storage Module (Key M 2280)

1. Locate the M.2 Key M slot and remove the screws on the board.



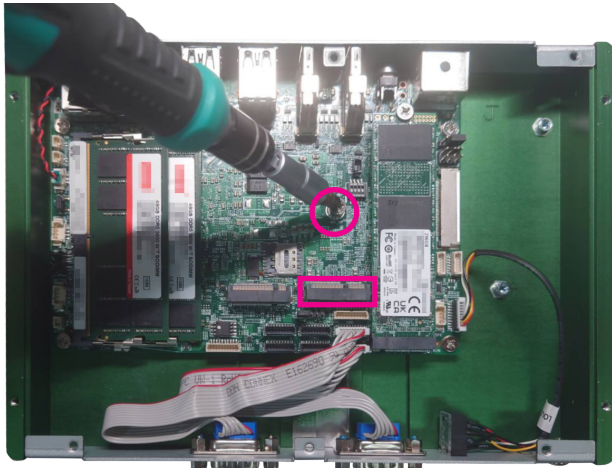
2. Insert the M.2 module into the M.2 slot at a 45-degree angle until the gold-plated connector on the edge of the module completely disappears into the slot.

3. Push the module down and secure it with the screw that was removed from step 1.



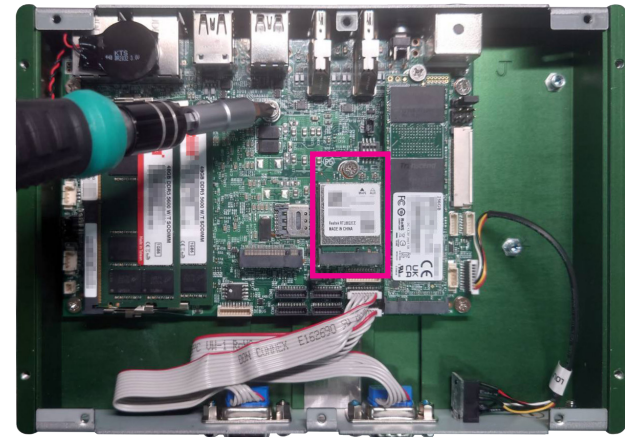
Installing an M.2 Wi-Fi Module (Key E 2230)

1. Locate the M.2 Key E slot and remove the screws on the board.



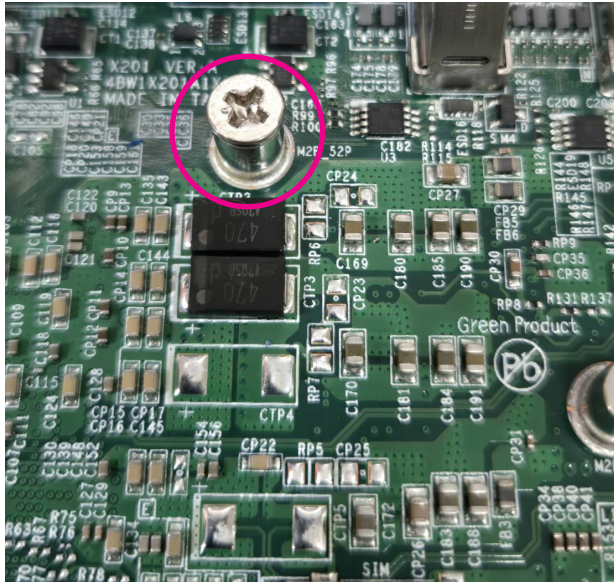
2. Insert the M.2 module into the M.2 slot at a 45-degree angle until the gold-plated connector on the edge of the module completely disappears into the slot.

3. Push the module down and secure it with the screw that was removed from step 1.

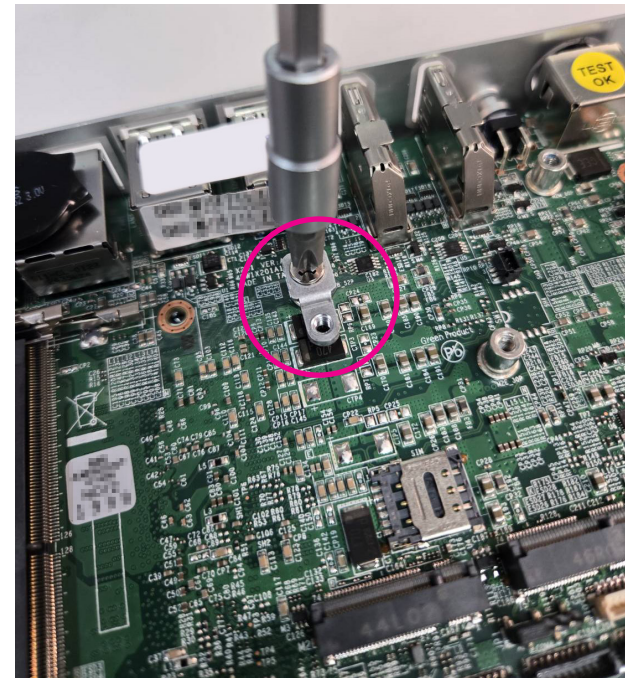


Installing an M.2 5G/LTE Module (Key B 3052/2242)

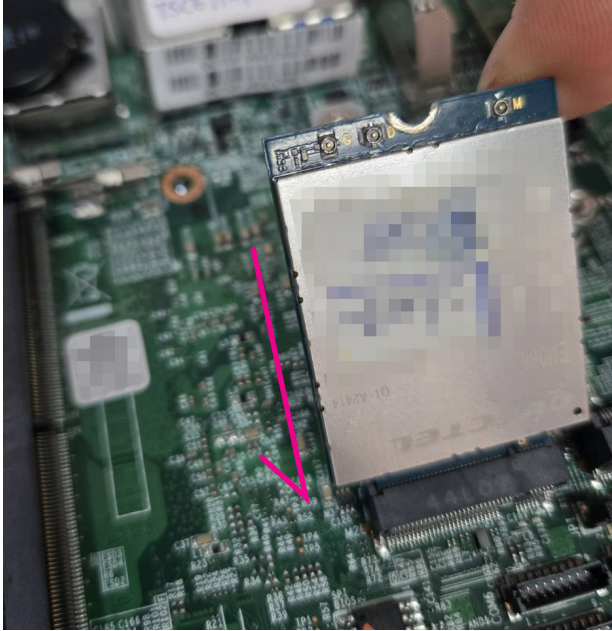
1. Remove the screw as shown below.



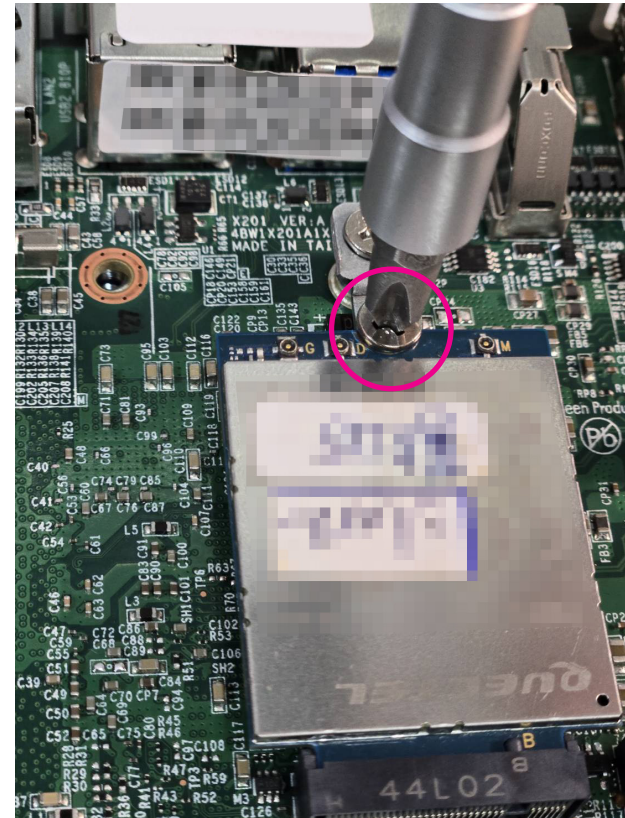
2. Pick up the M.2 extend nut bracket for LTE/5G module from the accessory box, then tighten it with the screw removed from step 1 on the motherboard.



3. Insert the module into the slot on the motherboard carefully.

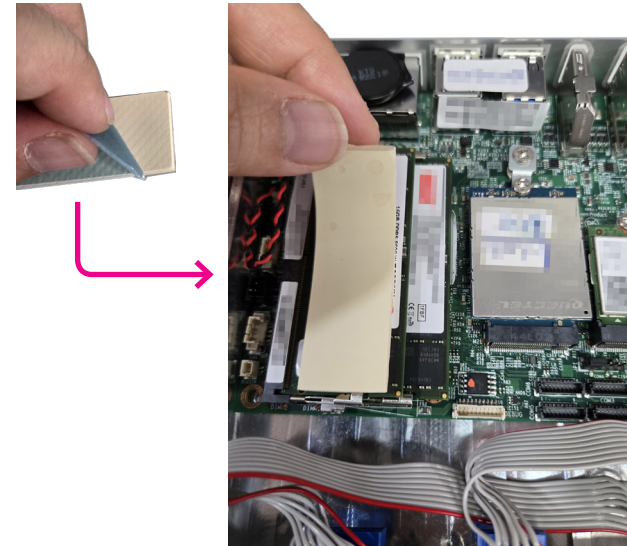
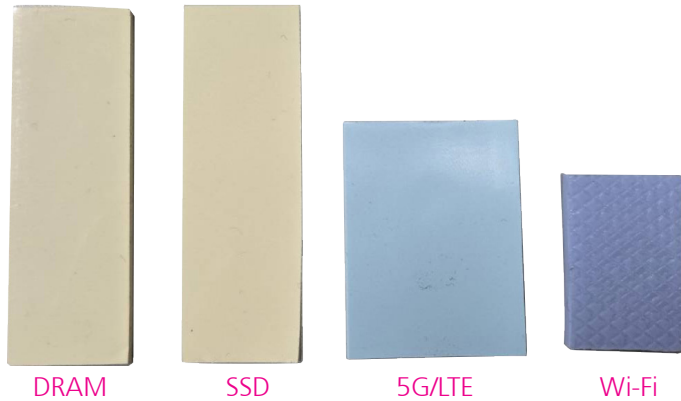


4. Pick up another screw from the accessory box and use it to tighten the module, as shown below.

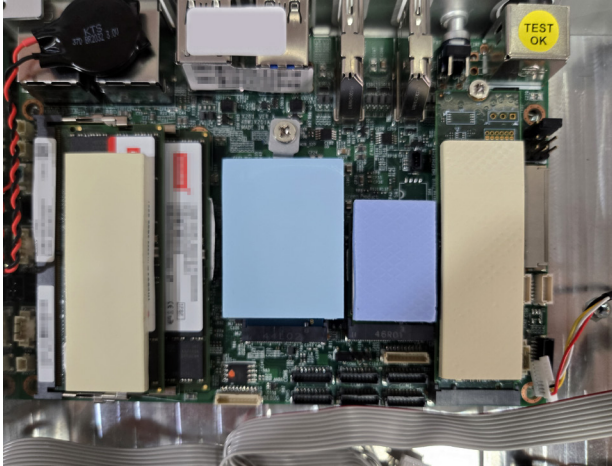


Installing the Thermal Pad for the Modules

1. Upon successful completion of the memory module installation outlined in the previous section, adhere the thermal pads according to the instructions in this section prior to chassis assembly.
2. Check the thermal pads in the accessory box.
3. Peel off the film attached to the thermal pad and apply it to the DRAM module.



4. Follow the same procedure to apply the remaining thermal pads to the communication and storage modules.



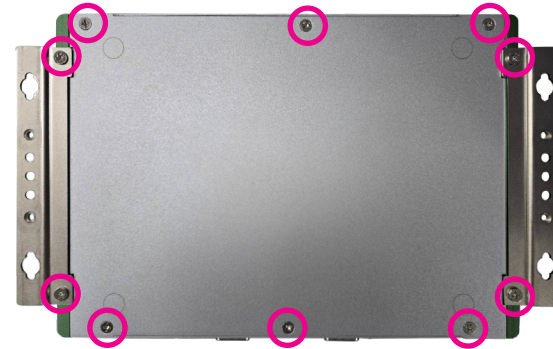
5. Refer to the next section for instructions on covering the bottom chassis.

Assembling the Bottom Cover

1. Make sure the bottom cover is facing the right direction.



2. Secure the bottom cover to the chassis firmly with the 6 screws (indicated in pink below), and use the 4 screws for the mounting bracket (marked in blue below) if necessary.



Wall mounting instruction

To mount the system on to a wall or some other surface using the two mounting brackets, please follow the steps below.

1. Refer to the [previous page](#) for instructions on screwing the mounting brackets.
2. Drill holes in the intended installation surface.
3. Align the mounting holes in the sides of the mounting brackets with the predrilled holes in the mounting surface.
4. Insert four retention screws, two in each bracket to secure the system to the wall.



Specification of the wall mount screw:
Round Head Screw w/ Spring+Flat Washer Long Fei:P3x6L P3x6
iso/SW6x0.5 NI



CHAPTER 4: BIOS SETUP

This chapter describes how to use the BIOS setup program for the NDiS B362. The BIOS screens provided in this chapter are for reference only and may change if the BIOS is updated in the future.

To check for the latest updates and revisions, visit the NEXCOM Web site at www.nexcom.com.tw.

About BIOS Setup

The BIOS (Basic Input and Output System) Setup program is a menu driven utility that enables you to make changes to the system configuration and tailor your system to suit your individual work needs. It is a ROM-based configuration utility that displays the system's configuration status and provides you with a tool to set system parameters.

These parameters are stored in non-volatile battery-backed-up CMOS RAM that saves this information even when the power is turned off. When the system is turned back on, the system is configured with the values found in CMOS.

With easy-to-use pull down menus, you can configure such items as:

- Hard drives, diskette drives, and peripherals
- Video display type and display options
- Password protection from unauthorized use
- Power management features

The settings made in the setup program affect how the computer performs. It is important, therefore, first to try to understand all the setup options, and second, to make settings appropriate for the way you use the computer.

When to Configure the BIOS

- This program should be executed under the following conditions:
 - When changing the system configuration
 - When a configuration error is detected by the system and you are prompted to make changes to the setup program
 - When resetting the system clock
 - When redefining the communication ports to prevent any conflicts
 - When making changes to the Power Management configuration
 - When changing the password or making other changes to the security setup

Normally, CMOS setup is needed when the system hardware is not consistent with the information contained in the CMOS RAM, whenever the CMOS RAM has lost power, or the system features need to be changed.

Default Configuration


Most of the configuration settings are either predefined according to the Load Optimal Defaults settings which are stored in the BIOS or are automatically detected and configured without requiring any actions. There are a few settings that you may need to change depending on your system configuration.

Entering Setup












When the system is powered on, the BIOS will enter the Power-On Self Test (POST) routines. These routines perform various diagnostic checks; if an error is encountered, the error will be reported in one of two different ways:

- If the error occurs before the display device is initialized, a series of beeps will be transmitted.
- If the error occurs after the display device is initialized, the screen will display the error message.

Powering on the computer and immediately pressing allows you to enter Setup.

Press the  key to enter Setup:


Legends

Key	Function
	Moves the highlight left or right to select a menu.
	Moves the highlight up or down between sub-menus or fields.
	Exits the BIOS Setup Utility.
	Scrolls forward through the values or options of the highlighted field.
	Scrolls backward through the values or options of the highlighted field.
	Selects a field.
	Displays General Help.
	Load previous values.
	Load optimized default values.
	Saves and exits the Setup program.
	Press <Enter> to enter the highlighted sub-menu


Scroll Bar

When a scroll bar appears to the right of the setup screen, it indicates that there are more available fields not shown on the screen. Use the up and down arrow keys to scroll through all the available fields.

Submenu

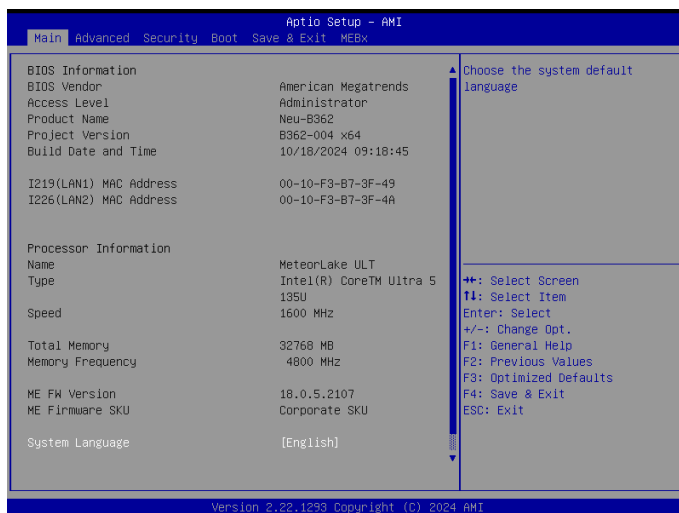
When “▶” appears on the left of a particular field, it indicates that a submenu which contains additional options are available for that field. To display the submenu, move the highlight to that field and press  .

BIOS Setup Utility

Once you enter the AMI BIOS Setup Utility, the Main Menu will appear on the screen. The main menu allows you to select from several setup functions and one exit. Use arrow keys to select among the items and press  to accept or enter the submenu.

Main

The Main menu is the first screen that you will see when you enter the BIOS Setup Utility.



System Date

The date format is <day>, <month>, <date>, <year>. Day displays a day, from Monday to Sunday. Month displays the month, from January to December. Date displays the date, from 1 to 31. Year displays the year, from 1999 to 2099.

System Time

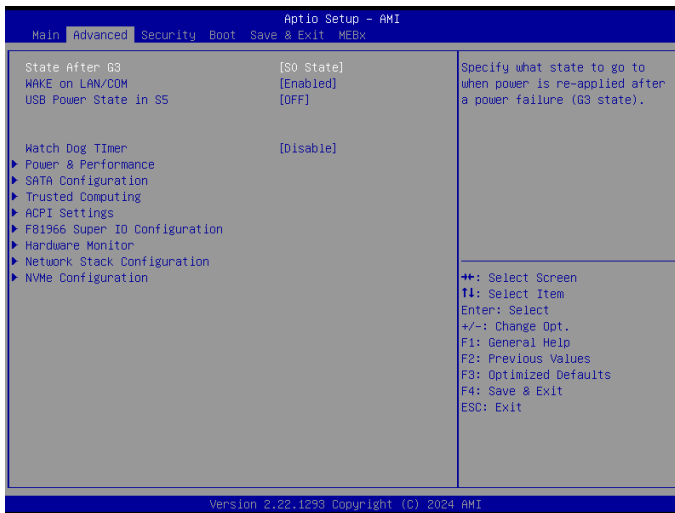
The time format is <hour>, <minute>, <second>. The time is based on the 24-hour military-time clock. For example, 1 p.m. is 13:00:00. Hour displays hours from 00 to 23. Minute displays minutes from 00 to 59. Second displays seconds from 00 to 59.

Advanced

The Advanced menu allows you to configure your system for basic operation. Some entries are defaults required by the system board, while others, if enabled, will improve the performance of your system or let you set some features according to your preference.



Setting incorrect field values may cause the system to malfunction.



State After G3

Specify what state to go to when power is re-applied after a power failure (G3 State).

WAKE on LAN/COM

Enable or disable the integrate LAN & COM port RI to wake the system.

USB Power State in S5

Configure the USB power state in S5.

Watch Dog Timer

Enable or disable the Watch Dog Timer function.

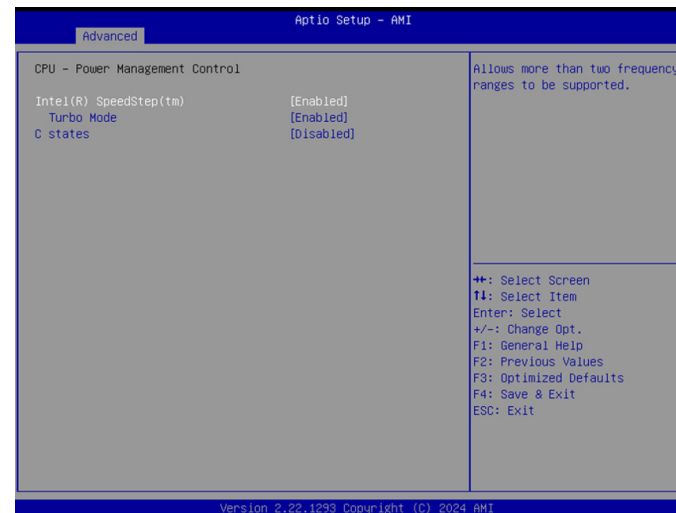
Power & Performance



CPU - Power Management Control

Enter the CPU - Power Management Control sub-menu.

CPU - Power Management Control



Intel® SpeedStep™

Enable or disable Intel SpeedStep.

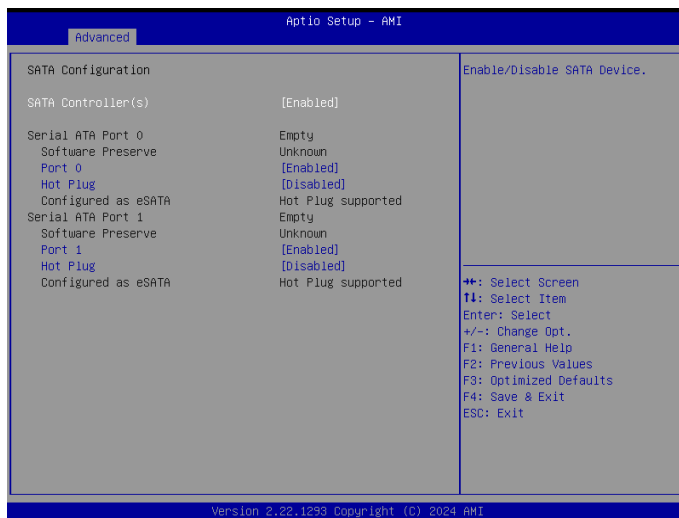
Turbo Mode

Enable or disable processor turbo mode. By default, it's enabled.

C states

Enable or disable CPU power management. Allow CPU to go to C states when it's not 100% utilized.

SATA Configuration



SATA Controller(s)

Enable or disable SATA device.

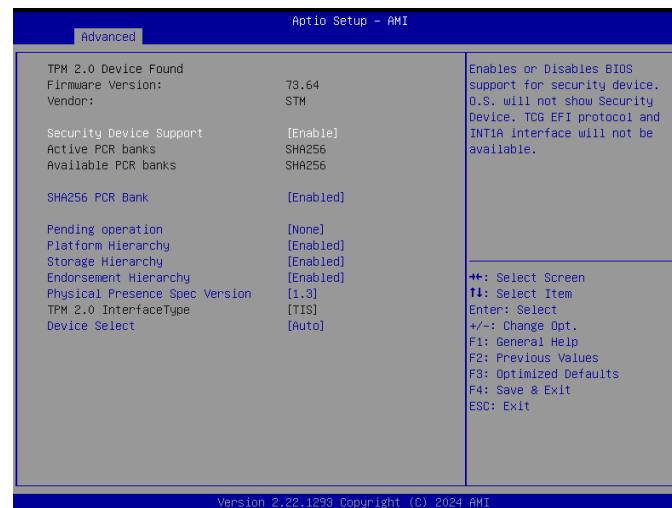
Port 0/1

Enable or disable SATA port.

Hot Plug 0/1

Enable or disable hot plugging feature.

Trusted Computing



Security Device Support

Enable or disable BIOS support for security device. O.S. will not show Security Device. TCG EFI protocol and INT1A interface will not be available.

SHA256 PCR Bank

Enable or disable SHA256 PCR Bank.

Pending operation

Schedule an operation for the security device.

Platform Hierarchy

Enable or disable platform hierarchy.

Storage Hierarchy

Enable or disable storage hierarchy.

Endorsement Hierarchy

Enable or disable endorsement hierarchy.

Physical Presence Spec Version

Configure the physical presence spec version.

Device Select

TPM 1.2 will restrict support to TPM 1.2 devices. TPM 2.0 will restrict support to TPM 2.0 devices. Auto will support both TPM 1.2 and 2.0 devices with the default set to TPM 2.0 devices if not found, and TPM 1.2 devices will be enumerated.

ACPI Settings



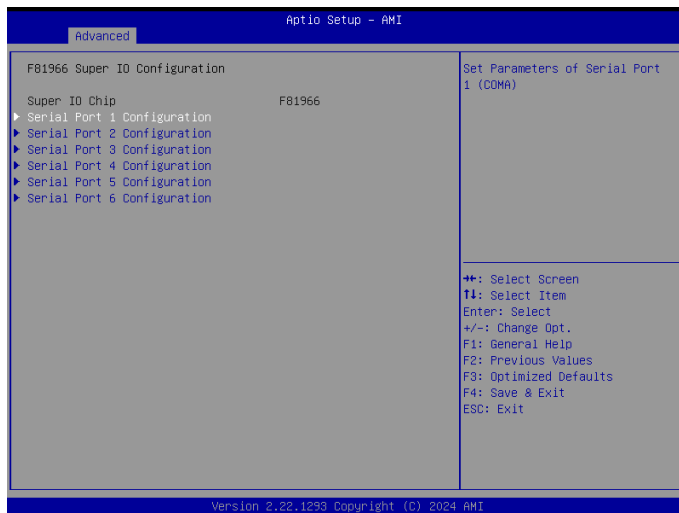
Wake system from S5

Enable or disable system wake on alarm event.

Select FixedTime: System will wake on the hr::min::sec specified.

Select DynamicTime: System will wake on the current time + increase minute(s).

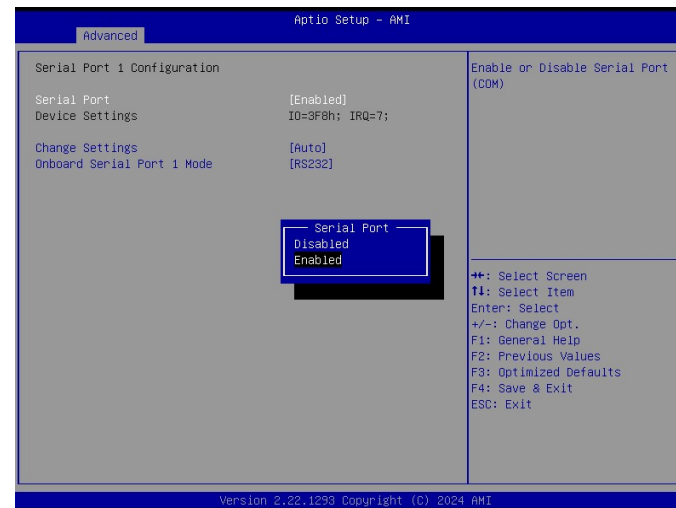
F81966 Super IO Configuration



Serial Port 1 Configuration

Enter the Serial Port 1 Configuration sub-menu.

Serial Port 1 Configuration



Serial Port

Enable or disable the serial port.

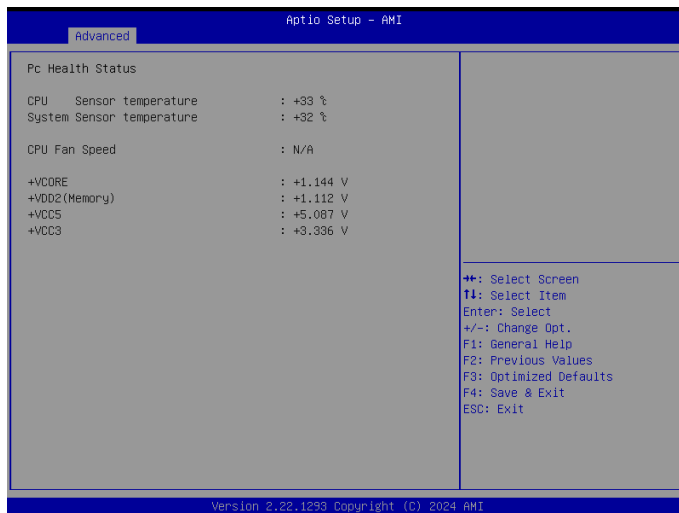
Change Settings

Select an optimal setting for the Super IO device.

Onboard Serial Port 1 Mode

This field is used to configure the mode of serial port 1 as RS232, RS422, or RS485.

Hardware Monitor



CPU Sensor Temp

Detect and display the current CPU temperature.

System Sensor Temperature

Detect and display the internal temperature of the system.

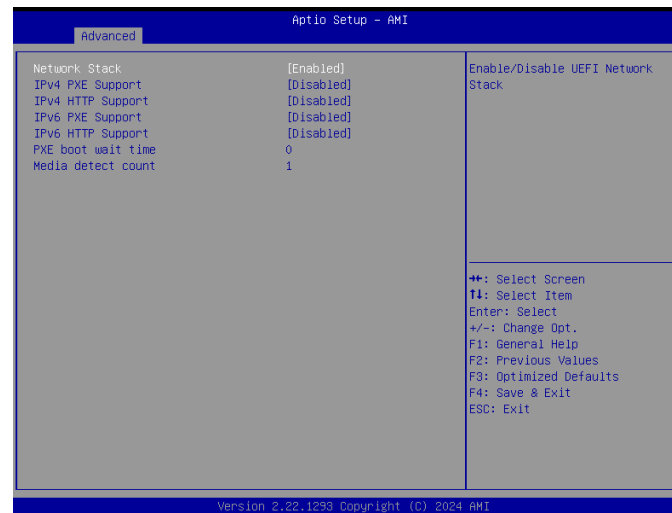
CPU Fan Speed

Detect and display the current CPU fan speed.

V CORE

Detect the CPU internal kernel voltage.

Network Stack Configuration



Network Stack

Enable or disable UEFI network stack.

IPv4 PXE Support

Enable or disable IPv4 PXE support. If disabled, the IPv4 boot option will not be created.

IPv4 HTTP Support

Enable or disable IPv4 HTTP support

IPv6 PXE Support

Enable or disable IPv6 PXE support. If disabled, the IPv6 boot option will not be created.

IPv6 HTTP Support

Enable or disable Ipv6 HTTP support.

PXE boot wait time

Configure the wait time to press the ESC key to abort the PXE boot.

Media detect count

Configure the number of times the media will be checked.

NVMe Configuration



NVMe Device

Enter the submenu of the connected NVMe device.

NVMe Device information



Run Device Self Test

Run the device self test according to the self test option and action selected. Pressing the Esc key will abort the test.

Self Test Option

Configure the method used for self test.

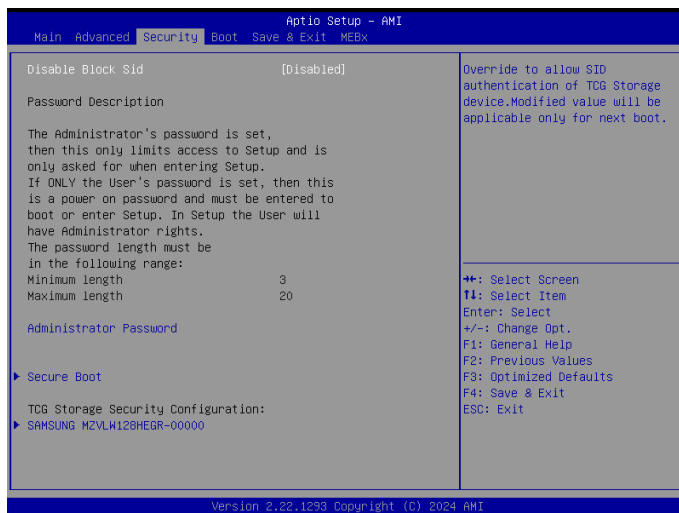
Short Short option will take couple of minutes to complete.

Extended Extended option will take several minutes to complete.

Self Test Action

Configure the items used for self test. Controller Only Test and Controller and NameSpace Test options are available. Selecting Controller and NameSpace Test will take longer to complete.

Security



Administrator Password

Select this to reconfigure the administrator's password.

Secure Boot

Enter the Secure Boot sub-menu.

TCG Storage Security Configuration

Configure the TCG storage security. The item shown here depends on the storage device you have connected.

Secure Boot



Secure Boot

Select this to enable or disable Secure Boot. Secure Boot only works when the system runs in user mode.

Secure Boot Mode

Select this to configure the Secure Boot mode.

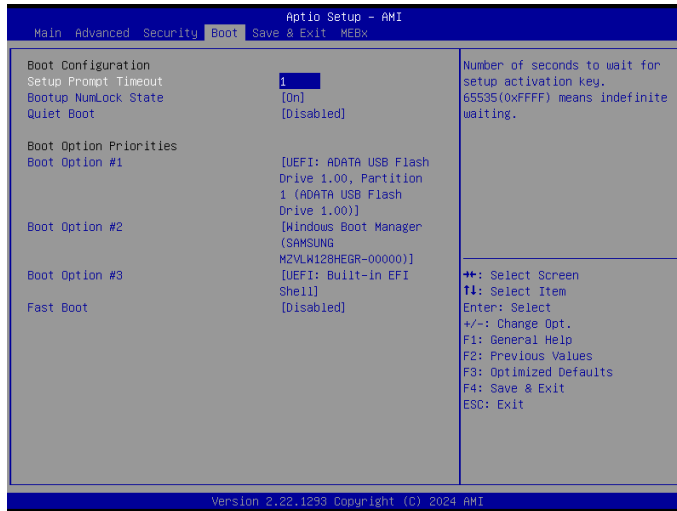
Standard

Fixed secure boot policy.

Custom

Secure boot policy variables can be configured by a physically present user without full authentication.

Boot



Boot Option Priorities

Adjust the boot sequence of the system. Boot Option #1 is the first boot device that the system will boot from, next will be #2 and so forth.

Fast Boot

When enabled, the BIOS will shorten or skip some check items during POST. This will decrease the time needed to boot the system.

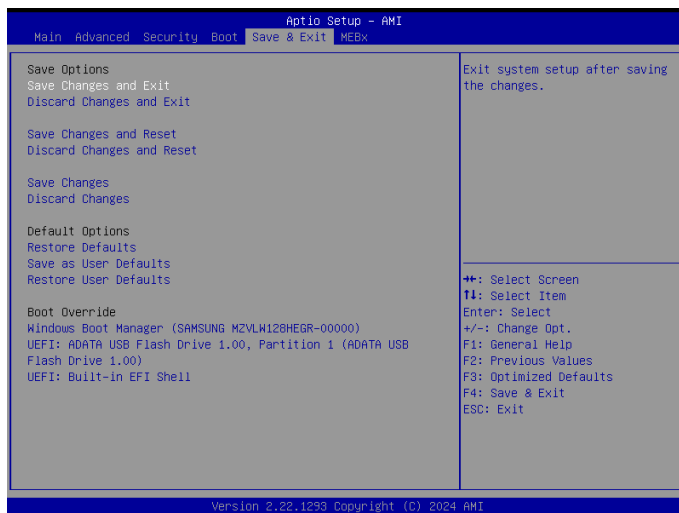
Setup Prompt Timeout

Number of seconds to wait for setup activation key. 65535(0xFFFF) means indefinite waiting.

Bootup NumLock State

This allows you to determine the default state of the numeric keypad. By default, the system boots up with NumLock on wherein the function of the numeric keypad is the number keys. When set to Off, the function of the numeric keypad is the arrow keys.

Save & Exit



Save Changes and Exit

To save the changes and reset, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.

Discard Changes and Exit

To exit the Setup utility and reset without saving the changes, select this field then press <Enter>. You may be prompted to confirm again before exiting.

Save Changes and Reset

To save the changes and reset, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.

Discard Changes and Reset

To exit the Setup utility without saving the changes, select this field then press <Enter>. You may be prompted to confirm again before exiting.

Save Changes

To save changes and continue configuring the BIOS, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.

Discard Changes

To discard the changes, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes to discard all changes made and restore the previously saved settings.

Restore Defaults

To restore the BIOS to default settings, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.

Save as User Defaults

To use the current configurations as user default settings for the BIOS, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.

Restore User Defaults

To restore the BIOS to user default settings, select this field then press <Enter>. A dialog box will appear. Confirm by selecting Yes.

Boot Override

To bypass the boot sequence from the Boot Option List and boot from a particular device, select the desired device and press <Enter>.